

# AURIX™ TC37x variants

## About this document

### Scope and purpose

This document is an addendum to the TC37x Product Data Sheet and User's Manual, listing all planned product variants, key parameters such as memory size and optional features.

The User's Manual lists functions implemented on the Silicon, but this document counts functions that are pinning dependent; i.e. functions are counted that are connected to at least one package pin. As pins are overlaid with several functions the pinning needs to be checked (see Product Data Sheet) to determine the number of usable functions in an application.

### Naming conventions

Prefix:

- SAK:  $T_{\text{ambient}}$  Temperature Range from -40 °C up to +125 °C.
- SAL:  $T_{\text{ambient}}$  Temperature Range from -40 °C up to +150 °C (packaged device).

Feature Package:

- P: Standard feature.
- E: Emulation device with all features of the emulated standard type, additionally full MCDS, overlay functionality for calibration, AGBT as trace interface for development (depending on the package). Refer to the Emulation devices Data Sheet for further details.
- C,I,V,Z: Customer Specific.
- A: ADAS ext. Memory.
- T: ADAS + emulation.
- X: Extended Feature device. These products contain the extended memory (EMEM) of the ADAS subsystem. The ADAS peripherals SPU and RIF are not available.
- M: MotionWise software.
- F: Extended Flash.
- G: Additional Connectivity.
- H: ADAS Standard feature.
- N: Standard feature with AMU.

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## 1 TC37x AA step variants

## 1 TC37x AA step variants

## 1.1 TC37x AA step (part 1)

A table listing the TC37x AA step variants.

Table 1 TC37x\_AA step (part 1)

SAL-TC377TP-96F300S	SAL-TC375TP-96F300W	SAK-TC377TP-96F300S	SAK-TC375TP-96F300W	SAK-TC377DP-96F300S	SAL-TC377DP-96F300S	SAK-TC375DP-96F300W
<b>Step</b>						
AA	AA	AA	AA	AA	AA	AA
<b>Production Status</b>						
Standard	Standard	Standard	Standard	Customer Specific	Customer Specific	Customer Specific
<b>Package Type</b>						
PG-LFBGA-292	PG-QFP-176	PG-LFBGA-292	PG-QFP-176	PG-LFBGA-292	PG-LFBGA-292	PG-QFP-176
<b>Pinout</b>						
LFBGA 0.8 mm	LQFP 0.5 mm	LFBGA 0.8 mm	LQFP 0.5 mm	LFBGA 0.8 mm	LFBGA 0.8 mm	LQFP 0.5 mm
<b>Reference Silicon</b>						
TC37x	TC37x	TC37x	TC37x	TC37x	TC37x	TC37x
<b>Temperature Range (Ambient)</b>						
SAL	SAL	SAK	SAK	SAK	SAL	SAK
<b>Chip ID</b>						
<b>Attention:</b> The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.						
0x89007780	0x89007580	0x89007780	0x89007580	0xC9007780	0xC9007780	0x89007580
<b>Cores / Checker Cores</b>						
3/2	3/2	3/2	3/2	2/2	2/2	2/2
<b>Max. Freq. (MHz)</b>						
300	300	300	300	300	300	300
<b>Program Flash (MB)</b>						
6	6	6	6	6	6	6
<b>Data Flash0 (single-ended) (KB)</b>						
256	256	256	256	256	256	256
<b>Total SRAM (without EMEM and Cache) (KB)</b>						
992	992	992	992	768	768	768
<b>EMEM Size (KB)</b>						
0	0	0	0	0	0	0

## 1 TC37x AA step variants

Table 1 TC37x\_AA step (part 1) (continued)

SAL-TC377TP-96F300S	SAL-TC375TP-96F300W	SAK-TC377TP-96F300S	SAK-TC375TP-96F300W	SAK-TC377DP-96F300S	SAL-TC377DP-96F300S	SAK-TC375DP-96F300W
<b>DSPR (KB)</b>						
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other	240 in CPU0&1; 96 other	240 in CPU0&1; 96 other	240 in CPU0&1	240 in CPU0&1	240 in CPU0&1; 96 other
<b>DLMU (KB)</b>						
64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU
<b>PSPR (KB)</b>						
64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU	64 per CPU
<b>LMU (KB)</b>						
0	0	0	0	0	0	0
<b>DAM (KB)</b>						
32	32	32	32	32	32	32
<b>AMU<sup>1)</sup></b>						
No	No	No	No	No	No	No
<b>ADC (Primary Groups/Channels)</b>						
4/32	4/25	4/32	4/25	4/32	4/32	4/25
<b>ADC (Secondary Groups/Channels)</b>						
4/60	4/45	4/60	4/45	4/60	4/60	4/45
<b>ADC (Fast Compare Channels)</b>						
4	4	4	4	4	4	4
<b>ADC (EDSADC Channels)</b>						
6	6	6	6	6	6	6
<b>CAN (Modules/Nodes)</b>						
2/2x4	2/2x4	2/2x4	2/2x4	2/2x4	2/2x4	2/2x4
<b>FlexRay (Modules/Channels)</b>						
1/1x2	1/1x2	1/1x2	1/1x2	1/1x2	1/1x2	1/1x2
<b>HSSL Modules</b>						
1	1	1	1	1	1	1
<b>ASCLIN Modules / with ASC &amp; LIN / with 3-wire SPI</b>						
12/12/11	12/12/10	12/12/11	12/12/10	12/12/11	12/12/11	12/12/10
<b>QSPI Modules / with LVDS</b>						

<sup>1</sup> AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

## 1 TC37x AA step variants

Table 1 TC37x\_AA step (part 1) (continued)

SAL-TC377TP-96F300S	SAL-TC375TP-96F300W	SAK-TC377TP-96F300S	SAK-TC375TP-96F300W	SAK-TC377DP-96F300S	SAL-TC377DP-96F300S	SAK-TC375DP-96F300W
5/2	5/2	5/2	5/2	5/2	5/2	5/2
<b>SENT Channels</b>						
15	15	15	15	15	15	15
<b>MSC Modules</b>						
2	2	2	2	2	2	2
<b>PSI5 Channels</b>						
2	2	2	2	2	2	2
<b>PSI5-S Module</b>						
Yes	Yes	Yes	Yes	Yes	Yes	Yes
<b>SDMMC Module</b>						
No	No	No	No	No	No	No
<b>Max. Ethernet Availability: 1Gbit/100Mbit/No</b>						
1Gbit/s	100Mbit/s (RMII)	1Gbit/s	100Mbit/s (RMII)	1Gbit/s	1Gbit/s	100Mbit/s (RMII)
<b>MCDS Availability</b>						
miniMCDS	miniMCDS	miniMCDS	miniMCDS	miniMCDS	miniMCDS	miniMCDS
<b>ADAS Cluster Available</b>						
No	No	No	No	No	No	No
<b>CIF</b>						
No	No	No	No	No	No	No
<b>HSM Available</b>						
Yes	Yes	Yes	Yes	Yes	Yes	Yes

## 1 TC37x AA step variants

### 1.2 TC37x AA step (part 2)

A continuation table listing the TC37x AA step variants.

**Table 2 TC37x\_AA step (part 2)**

SAL-TC375DP-96F300W	SAK-TC375TI-96F300W	SAL-TC375TI-96F300W
<b>Step</b>		
AA	AA	AA
<b>Production Status</b>		
Customer Specific	Customer Specific	Customer Specific
<b>Package Type</b>		
PG-QFP-176	PG-QFP-176	PG-QFP-176
<b>Pinout</b>		
LQFP 0.5 mm	LQFP 0.5 mm	LQFP 0.5 mm
<b>Reference Silicon</b>		
TC37x	TC37x	TC37x
<b>Temperature Range (Ambient)</b>		
SAL	SAK	SAL
<b>Chip ID</b>		
<i>Attention: The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.</i>		
0x89007580	0xE9007580	0xE9007580
<b>Cores / Checker Cores</b>		
2/2	3/2	3/2
<b>Max. Freq. (MHz)</b>		
300	300	300
<b>Program Flash (MB)</b>		
6	6	6
<b>Data Flash0 (single-ended) (KB)</b>		
256	256	256
<b>Total SRAM (without EMEM and Cache) (KB)</b>		
768	992	992
<b>EMEM Size (KB)</b>		
0	0	0
<b>DSPR (KB)</b>		
240 in CPU0&1; 96 other	240 in CPU0&1; 96 other	240 in CPU0&1; 96 other
<b>DLMU (KB)</b>		
64 per CPU	64 per CPU	64 per CPU

## 1 TC37x AA step variants

Table 2 TC37x\_AA step (part 2) (continued)

	SAL-TC375DP-96F300W	SAK-TC375TI-96F300W	SAL-TC375TI-96F300W
<b>PSPR (KB)</b>	64 per CPU	64 per CPU	64 per CPU
<b>LMU (KB)</b>	0	0	0
<b>DAM (KB)</b>	32	32	32
<b>AMU<sup>2)</sup></b>	No	No	No
<b>ADC (Primary Groups/Channels)</b>	4/25	4/25	4/25
<b>ADC (Secondary Groups/Channels)</b>	4/45	4/45	4/45
<b>ADC (Fast Compare Channels)</b>	4	4	4
<b>ADC (EDSADC Channels)</b>	6	6	6
<b>CAN (Modules/Nodes)</b>	2/2x4	2/2x4	2/2x4
<b>FlexRay (Modules/Channels)</b>	1/1x2	1/1x2	1/1x2
<b>HSSL Modules</b>	1	1	1
<b>ASCLIN Modules / with ASC &amp; LIN / with 3-wire SPI</b>	12/12/10	12/12/10	12/12/10
<b>QSPI Modules / with LVDS</b>	5/2	5/2	5/2
<b>SENT Channels</b>	15	15	15
<b>MSC Modules</b>	2	2	2
<b>PSI5 Channels</b>	2	2	2

<sup>2)</sup> AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

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**1 TC37x AA step variants**
**Table 2 TC37x\_AA step (part 2) (continued)**

<b>SAL-TC375DP-96F300W</b>	<b>SAK-TC375TI-96F300W</b>	<b>SAL-TC375TI-96F300W</b>
<b>PSI5-S Module</b>		
Yes	Yes	Yes
<b>SDMMC Module</b>		
No	No	No
<b>Max. Ethernet Availability: 1Gbit/100Mbit/No</b>		
100Mbit/s (RMII)	100Mbit/s (RMII)	100Mbit/s (RMII)
<b>MCDS Availability</b>		
miniMCDS	miniMCDS	miniMCDS
<b>ADAS Cluster Available</b>		
No	No	No
<b>CIF</b>		
No	No	No
<b>HSM Available</b>		
Yes	Yes	Yes



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## 2 Memory maps of TC37x variants

### 2 Memory maps of TC37x variants

This section describes the influence of the available feature variants on the memory map.

#### Cores / checker cores

Variants:

- 3/2: umbrella, see User's Manual.
- 2/2: reduced CPU variant, not available is CPU2 including its RAMs (DSPR, DCACHE, DTAG, PSPR, PCACHE, PTAG, DLMU).

#### HSM

Variants:

- Yes: umbrella, see User's Manual.
- No: HSM and DF1 are not available.

#### Ethernet availability

- 1Gbit/s: umbrella, see User's Manual.
- 100Mbit/s (RMII): due to pin limitations in this package the GETH module can be only used in RMII mode.

#### ADC availability

- Limitation on availability of ADC channels are caused by pin limitations. See Data Sheet for the pinning table of the package.

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**Revision history**
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Document version	Date of release	Description of changes
V1.0	2019-02-05	<ul style="list-style-type: none"> <li>First release.</li> </ul>
V1.1	2019-03-01	<ul style="list-style-type: none"> <li>Removed devices: SAK-TC377T-96F300S and SAK-TC375T-96F300W.</li> <li>Added devices: SAK-TC377DP-96F300S and SAL-TC377DP-96F300S.</li> </ul>
V1.2	2019-06-12	<ul style="list-style-type: none"> <li>Chapter 1: TC37x AA step variants table format changed to fit all the contents.</li> <li>Chapter 1: Added new row in the variant tables called "AMU" with the footnote for additional details.</li> <li>Chapter: About this document: Feature package definitions are updated to consistent with the product naming nomenclature definition.</li> </ul>
V1.3	2020-01-10	<ul style="list-style-type: none"> <li>Chapter 1: New TC37x AA step variants added: SAK-TC375DP-96F300W, SAL-TC375DP-96F300W .</li> <li>Page 1: About the document: Feature Package 'X' definition is updated to remove CIF.</li> <li>Chapter 1: Added new row in the variant tables called "CIF" indicating the Camera Interface availability.</li> </ul>
V1.4	2020-04-30	<ul style="list-style-type: none"> <li>Chapter 1: New TC37x AA step variants added: SAK-TC375TI-96F300W, SAL-TC375TI-96F300W .</li> <li>About this document section: Added an additional note for the Feature package 'E'.</li> </ul>
V1.5	2020-11-18	<ul style="list-style-type: none"> <li>Chapter 1: Removed Bare Die Marking variant SAL-TC370TP-96F300.</li> </ul>

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